

## General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Z series is integrated with fast recovery diode (FRD) to minimize reverse recovery time. It is suitable for resonant switching topologies to reach higher efficiency, higher reliability and smaller form factor.

## Features

- Low  $R_{DS(on)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Ultra-fast and robust body diode



## Applications

- PC power
- Telecom power
- Server power
- EV Charger
- Motor driver

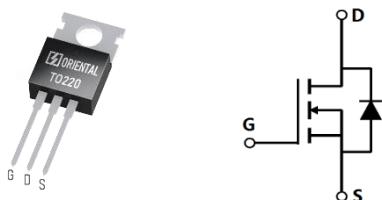
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS}$ , min @ $T_j(max)$	700	V
$I_D$ , pulse	75	A
$R_{DS(ON)}$ , max @ $V_{GS}=10V$	125	mΩ
$Q_g$	40.3	nC

## Marking Information

Product Name	Package	Marking
OSG65R125PZF	TO220	OSG65R125PZ

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	650	V
Gate-source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_D$	25	A
Continuous drain current <sup>1)</sup> , $T_C=100\text{ }^\circ\text{C}$		16	
Pulsed drain current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{D,\text{pulse}}$	75	A
Continuous diode forward current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_S$	25	A
Diode pulsed current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{S,\text{pulse}}$	75	A
Power dissipation <sup>3)</sup> , $T_C=25\text{ }^\circ\text{C}$	$P_D$	219	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	1000	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\ldots 480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\ldots 480\text{ V}$ , $I_{SD} \leq I_D$	dv/dt	50	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.57	$^\circ\text{C/W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	$^\circ\text{C/W}$

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	650			V	$V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$
		700				$V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$ , $T_j=150\text{ }^\circ\text{C}$
Gate threshold voltage	$V_{GS(\text{th})}$	3.0		4.5	V	$V_{DS}=V_{GS}$ , $I_D=1\text{ mA}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		0.115	0.125	$\Omega$	$V_{GS}=10\text{ V}$ , $I_D=12.5\text{ A}$
			0.2			$V_{GS}=10\text{ V}$ , $I_D=12.5\text{ A}$ , $T_j=150\text{ }^\circ\text{C}$
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	$I_{DSS}$			10	$\mu\text{A}$	$V_{DS}=650\text{ V}$ , $V_{GS}=0\text{ V}$

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		2681.3		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=100 kHz
Output capacitance	C <sub>oss</sub>		165.3		pF	
Reverse transfer capacitance	C <sub>rss</sub>		7.4		pF	
Turn-on delay time	t <sub>d(on)</sub>		73.0		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, R <sub>G</sub> =2 Ω, I <sub>D</sub> =20 A
Rise time	t <sub>r</sub>		91.4		ns	
Turn-off delay time	t <sub>d(off)</sub>		87.3		ns	
Fall time	t <sub>f</sub>		38.4		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		40.3		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, I <sub>D</sub> =20 A
Gate-source charge	Q <sub>gs</sub>		13.5		nC	
Gate-drain charge	Q <sub>gd</sub>		14.7		nC	
Gate plateau voltage	V <sub>plateau</sub>		7.1		V	

### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.3	V	I <sub>s</sub> =25 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		131		ns	
Reverse recovery charge	Q <sub>rr</sub>		0.8		uC	
Peak reverse recovery current	I <sub>rrm</sub>		11.9		A	

### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=100 V, V<sub>GS</sub>=10 V, L=60 mH, starting T<sub>j</sub>=25 °C.

## Electrical Characteristics Diagrams

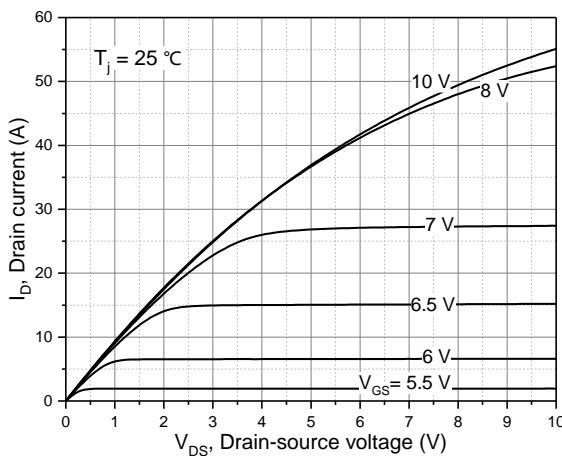


Figure 1. Typ. output characteristics

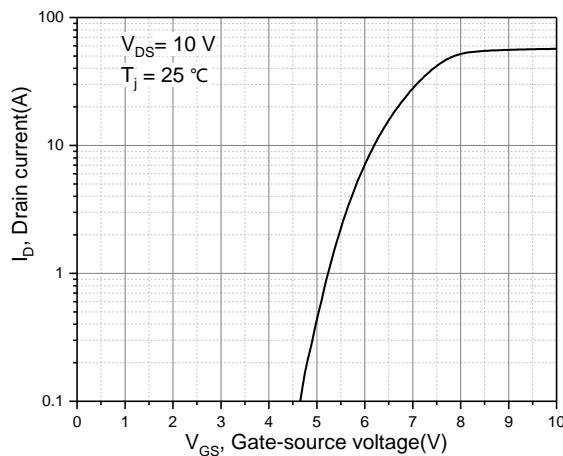


Figure 2. Typ. transfer characteristics

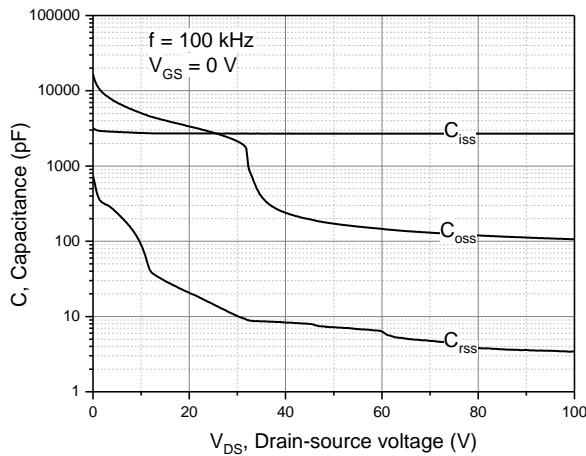


Figure 3. Typ. capacitances

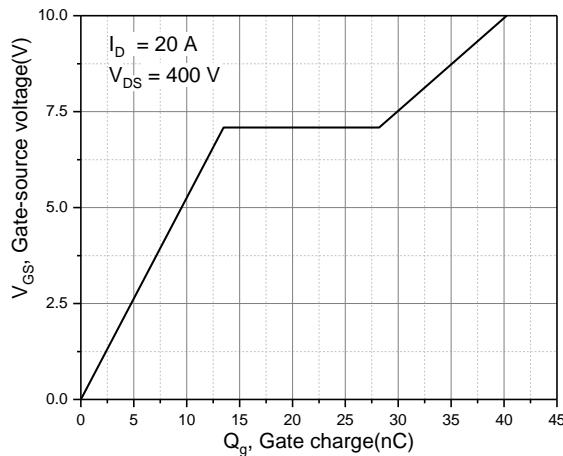


Figure 4. Typ. gate charge

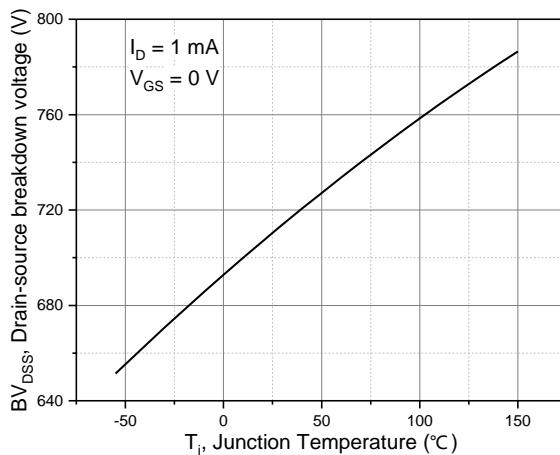


Figure 5. Drain-source breakdown voltage

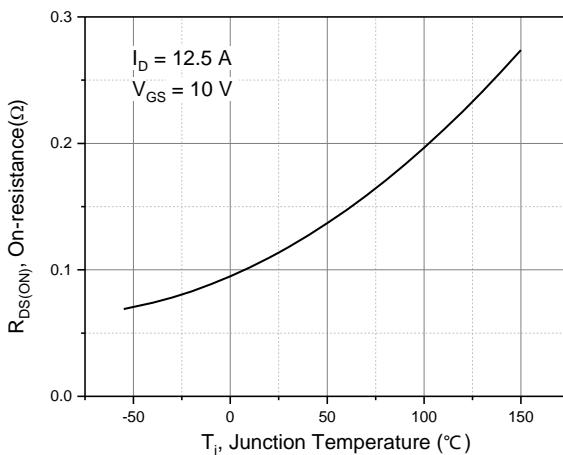
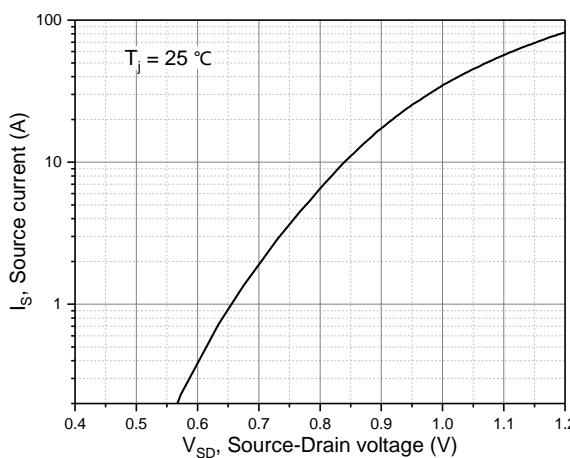
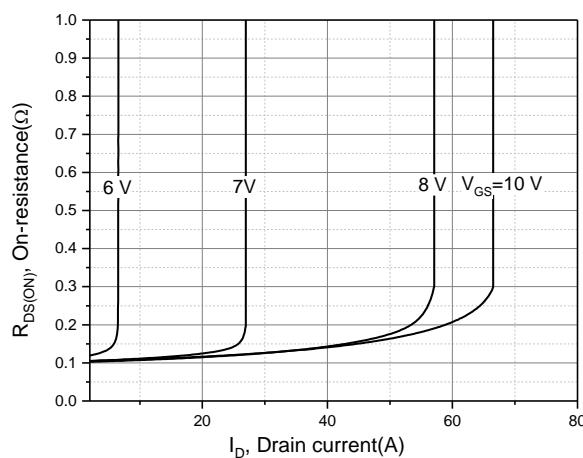


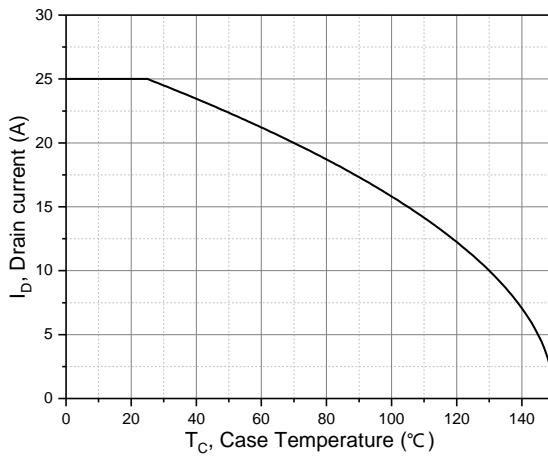
Figure 6. Drain-source on-state resistance



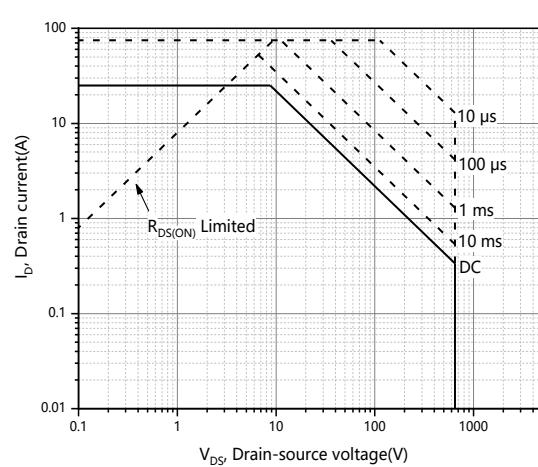
**Figure 7. Forward characteristic of body diode**



**Figure 8. Drain-source on-state resistance**

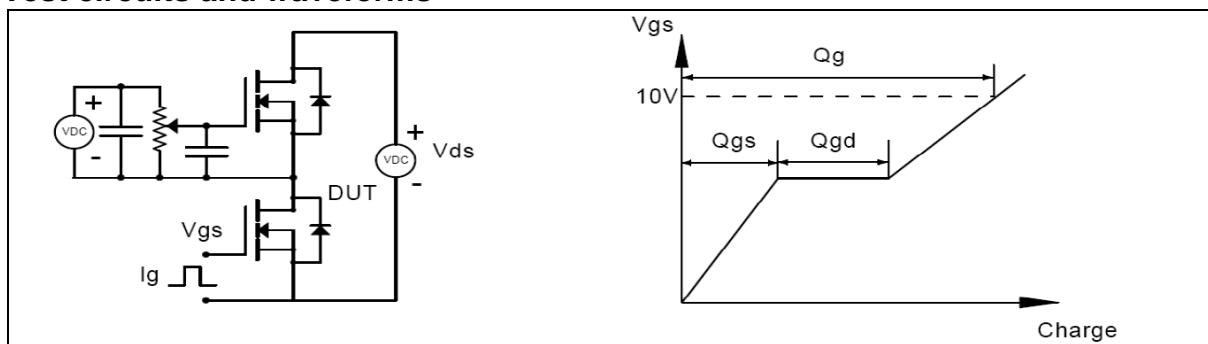


**Figure 9. Drain current**

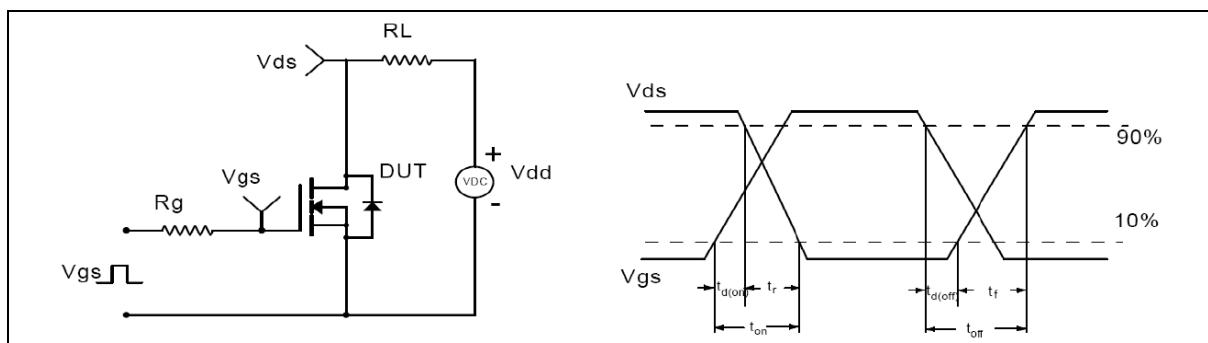


**Figure 10. Safe operation area T<sub>c</sub>=25 °C**

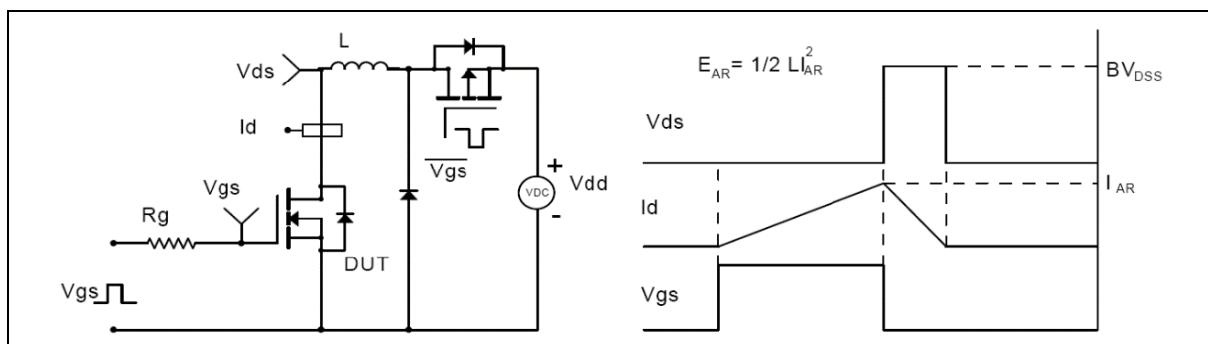
### Test circuits and waveforms



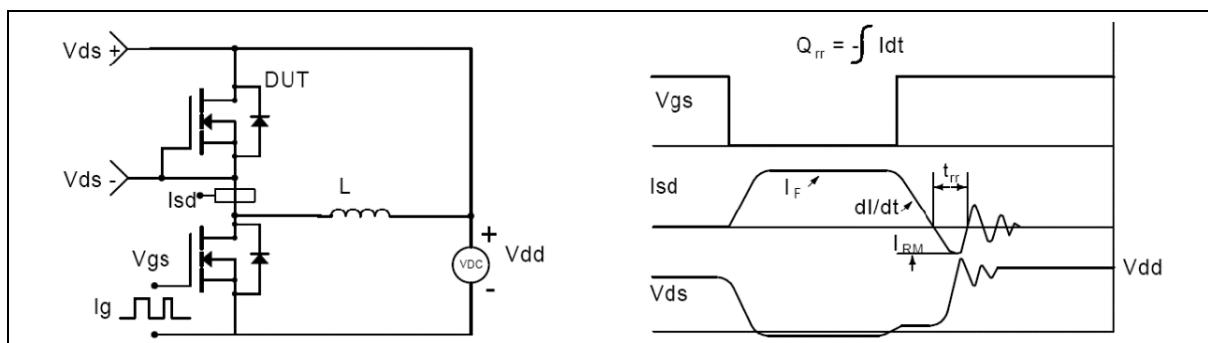
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

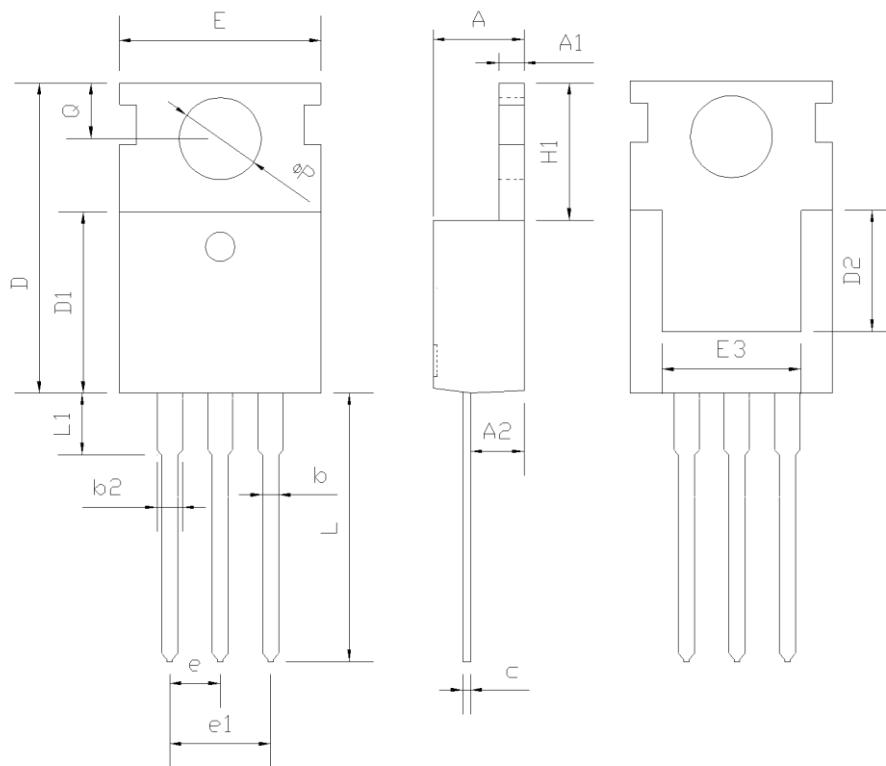


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

### Package Information



Symbol	mm		
	Min	Nom	Max
A	4.37	4.57	4.77
A1	1.25	1.30	1.45
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b2	1.17	1.27	1.47
c	0.40	0.50	0.65
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50	-	-
E	9.70	10.00	10.30
E3	7.00	-	-
e	2.54 BSC		
e1	5.08 BSC		
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1	-	3.10	3.40
ΦP	3.40	3.60	3.80
Q	2.60	2.80	3.00

Version1: TO220-P package outline dimension

## Ordering Information

Package Type	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO220-P	50	20	1000	6	6000

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R125PZF	TO220	yes	yes	yes

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